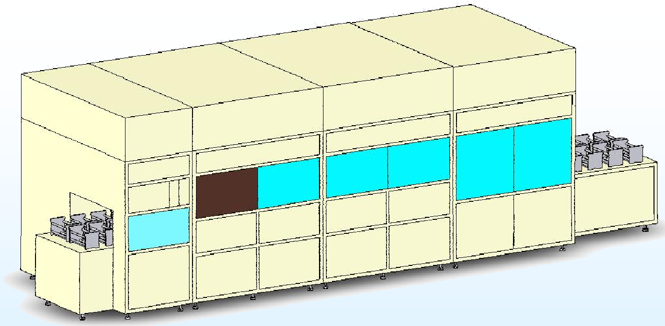
Equipments	**Batch Type Texture Processer for Mono Crystal Silicon**		
Wafers	**Mono Crystal Silicon** **□125mm (5 Inch)** **□156mm (6 Inch)**		
Throughput (200wafers/Batch)	**Standard**	**1,500 wafers/h**	
	High Throughput	**1,900 wafers/h**	
Processing	**Pre Clean ⇒ SDE ⇒ TEX ⇒ Metal Removal ⇒ Oxide Removal**		
Function	**Auto loading / unloading**		
	Auto transportation		
	Auto chemical supplying		
	Auto chemical exchange		
	Lot log data collection		
	Gravimetry (Option)		

Improvement of productivity

2008		2009
Standard Throughput 1500wafers/hr □125：2.54W/wafer≒33MW/year □156：4.09W/wafer≒54MW/year	▶	**Standard Throughput** 1500wafers/hr □125：2.54W/wafer≒33MW/year □156：4.09W/wafer≒54MW/year
No High Throughput Model	▶	**High Throughput** 1900wafers/hr (vs. Standard：+40%) □125：2.54W/wafer≒42MW/year □156：4.09W/wafer≒68MW/year

Feature

◆High speed and establishment of a large quantity of processing systems
◆Reduction of the wafer breaking rate with the original carrier
◆Adoption of the modularization design
⇒Shortening of the lead time and customized correspondence are possible